

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YOICHI KAMIKORIYAMA	02/21/2018
SHINICHI YAMAUCHI	02/21/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MITSUI MINING & SMELTING CO., LTD.
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<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	141-8584
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15761113
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	8007-1403
<b>NAME OF SUBMITTER:</b>	ERIC JENSEN
<b>SIGNATURE:</b>	/Eric Jensen/
<b>DATE SIGNED:</b>	03/19/2018
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 1</b>	
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## ASSIGNMENT AND INVENTOR'S DECLARATION

WHEREAS I/we, the undersigned inventor(s), hereafter also referred to as "assignor(s)", have invented certain new and useful improvements described in the application identified below; and

WHEREAS, Mitsui Mining & Smelting Co., Ltd., hereinafter referred to as "assignee(s)", whose address is 1-11-1 Osaki, Shinagawa-ku, Tokyo 1418584, Japan, is desirous of acquiring the entire right, title and interest in and to the application and invention, and to any United States patents to be obtained therefor;

NOW, THEREFORE, for valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/we, the above-named assignor(s), hereby sell, assign and transfer to the above named assignee(s), its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, including any right to bring or maintain an action for infringement under the provisional rights granted pursuant to Title 35, Section 154 of the United States Code or any other cause of action for acts which would constitute infringement occurring prior to this assignment, and including the right to claim priority under the International Convention of Paris (1883), as amended, of or in any corresponding foreign patent application, and I/we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee(s), its successors and assigns.

As a below named inventor, I hereby declare that:

This assignment and  
declaration is directed to:

- ☐ The attached application, or  
☒ United States Application or PCT International Application Number  
PCT/JP2016/078946 filed on September 29, 2016

The application is entitled: **BONDING JUNCTION STRUCTURE**

The above-identified application was made or was authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this assignment with declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

Given Name(s)	Yoichi	Family Name/Surname(s)	KAMIKORIYAMA
Inventor's Signature:	Yoichi Kamikoriyama	Date	2018.2.21
Given Name(s)	Shinichi	Family Name/Surname(s)	YAMAUCHI
Inventor's Signature:	Shinichi Yamauchi	Date	2018.2.21